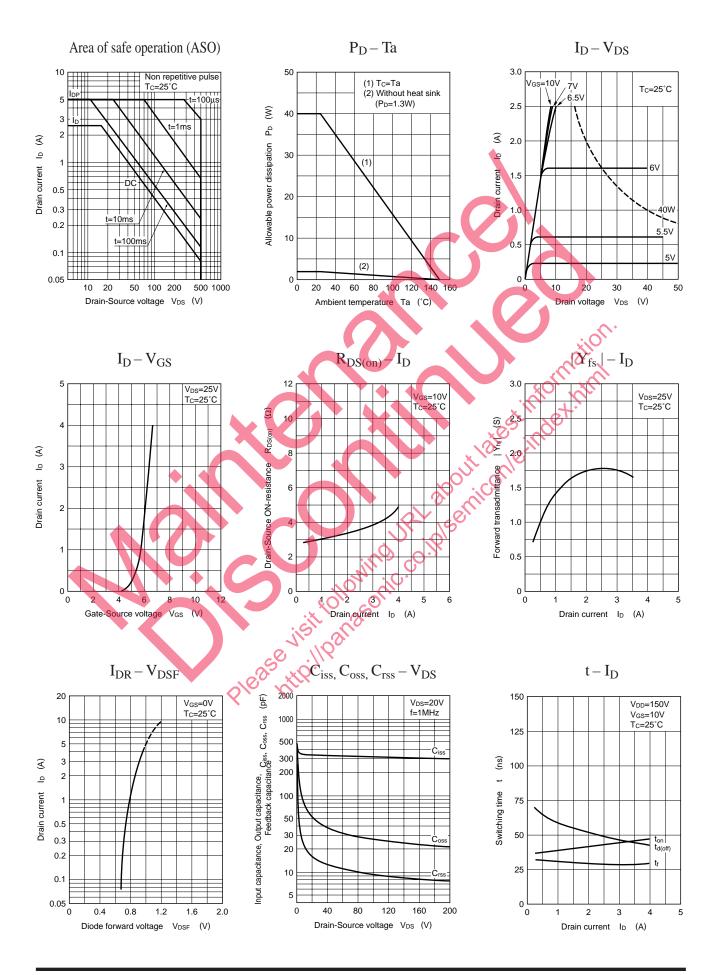
## 2SK2509

## Silicon N-Channel Power F-MOS

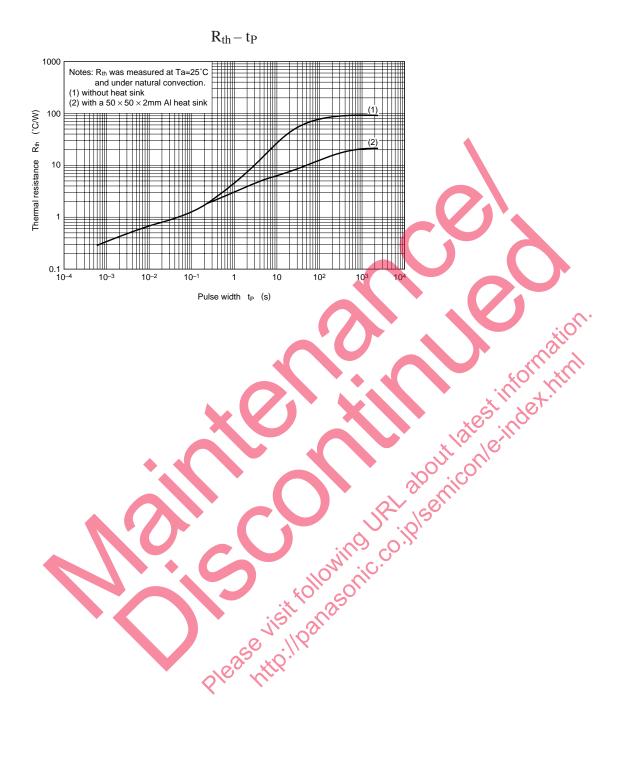


Parameter	Symbol	Condition	Min	Тур	Max	Unit
Drain-Source cut-off current	I <sub>DSS</sub>	$V_{DS} = 400V, V_{GS} = 0$			100	μΑ
Gate-Source leakage current	IGSS	$V_{GS}=\pm 30V, V_{DS}=0$			±1	μΑ
Drain-Source breakdown voltage	V <sub>DSS</sub>	$I_D=1mA$ , $V_{GS}=0$	500			V
Gate threshold voltage	V <sub>th</sub>	$V_{DS}=25V, I_D=1mA$	2		5	V
Drain-Source ON-resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =1.5A		3.2	4	Ω
Forward transadmittance	Y <sub>fs</sub>	$V_{DS}=25V, I_{D}=1.5A$	1	1.5		S
Diode forward voltage	V <sub>DSF</sub>	$I_{DR}=2.5A, V_{GS}=0$			-1.5	V
Input capacitance	C <sub>iss</sub>			330		pF
Output capacitance	Coss	$V_{DS}=20V, V_{GS}=0, f=1MHz$		55		pF
Feedback capacitance	C <sub>rss</sub>			20		pF
Turn-on time (delay time)	t <sub>d(on)</sub>			15		ns
Rise time	t <sub>r</sub>	V <sub>DD</sub> =150V, I <sub>D</sub> =1.5A		25		ns
Fall time	t <sub>f</sub>	$V_{GS}=10V, R_L=100\Omega$		30		ns
Turn-off time (delay time)	t <sub>d(off)</sub>			55		ns
Channel-Case heat resistance	R <sub>th(ch-c)</sub>				3.125	°C/W
Channel-Atmosphere heat resistance	R <sub>th(ch-a)</sub>				96.15	°C/W





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